



IPC-A-610G-R

Rail Transit Addendum to IPC-A-610G Acceptability of Electronic Assemblies

Developed by the IPC-A-610 Addendum for High Speed Railway
Task Group (7-31r) of the Product Assurance Committee (7-30) of IPC

Users of this publication are encouraged to participate in the
development of future revisions.

Contact:

IPC

Tel 847 615.7100
Fax 847 615.7105

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Acceptability of Electronic Assemblies

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1 General

For the purpose of this Addendum, the following topics are addressed in this section.

1.1 Scope

1.3 Classification

1.7 Order of Precedence

1 General (Cont.)

1.1 Scope This Addendum provides additional requirements specified for rail transit applications over those published in IPC-A-610G. It prescribes the practices and requirements for the manufacture of electronic assemblies in rail transit industry, and applies to Class 3 to ensure industry-specific high reliability and environmental adaptability.

This Addendum is used in conjunction with IPC-A-610G.

For the purpose of this Addendum, if a conflict occurs between the English version and other versions of this document, the English version will take precedence.

This Addendum particularly supplements or replaces Class 3 requirements in IPC-A-610G. Clauses not involved and requirements not mentioned, i.e., Class 1, 2 requirements, are subject to the corresponding provisions of IPC-A-610G.

The clauses modified by this Addendum do not include subordinate clauses unless specifically stated, i.e., changes made to 1.7 do not affect 1.7.1 unless 1.7.1 is also addressed in this Addendum.

When a paragraph refers to an entire section, e.g., the first paragraph in Section 10 of this Addendum, it's the responsibility of the Addendum users to determine which clauses from that section, e.g., 10.2.2, are used from IPC-A-610G and which clauses are covered by this Addendum.

Tables/Figures, including newly added as well as original or modified from IPC-A-610G, in a section in this Addendum are numbered from "1R", e.g., Table 7-1R, and Figure 7-1R, 7-2R in section 7.

This Addendum does not specify frequency of in-process or frequency of end-product inspection. No limit is placed on the number of Process Indicators or the number of allowable repair/rework of Defects. Such information should be developed with a SPC plan (see IPC-9191). Whenever special process is involved, e.g., soldering, crimp, ISO/TS 22163:2017 and relevant documents **shall** apply.

1.3 Classification Use of this Addendum applies to Class 3 by default. See IPC-A-610G 1.3 for product classification and the definition of Class 3. In general, the criteria in this Addendum are more stringent or applicable to rail transit than the criteria for Class 3 in IPC-A-610G.

Determination of Class relates to manufacturability, complexity, function and performance requirements, and the frequency of validation (inspection/test). The User or the Designer has the ultimate responsibility for identifying the Class to which the assembly is evaluated. If the User does not establish and document the acceptance Class, the Manufacturer may do so.

1.7 Order Of Precedence In the event of conflict, the following order of precedence applies:

- 1) Procurement as agreed between User and Manufacturer.
- 2) Engineering documentation reflecting the User's detailed requirement or end-use requirement.
- 3) When invoked by the User or per contractual agreement, this Addendum.

In case a conflict between this Addendum and the referenced documents, this Addendum takes precedence. If a referenced document or its version in this Addendum differs from that in IPC-A-610G, the one in this Addendum takes precedence.

The User has the opportunity to specify alternate acceptance criteria.